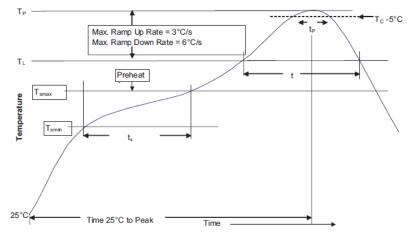
Magnetics soldering profile

Solder reflow profile- Surface mount components

Wave soldering not recommended



-_{Tc-5°C} Table 1 - Standard SnPb Solder (T_C)

| Package Thickness | Volume mm3 <350 | Volume mm3 ≥350 |
|----------------------|-----------------------|-----------------------|
| <2.5mm) | 235°C | 220°C |
| ≥2.5mm | 220°C | 220°C |

Table 2 - Lead (Pb) Free Solder (T_C)

| Package Thickness | Volume mm³ <350 | Volume mm³ 350 - 2000 | Volume mm³ >2000 |
|----------------------|-----------------------|-----------------------------|------------------------|
| <1.6mm | 260°C | 260°C | 260°C |
| 1.6 - 2.5mm | 260°C | 250°C | 245°C |
| >2.5mm | 250°C | 245°C | 245°C |

Reference JDEC J-STD-020D

| Profile Feature | Standard SnPb Solder | Lead (Pb) Free Solder |
|----------------------------------------------------------------------------------------------------|-------------------------|-------------------------|
| Preheat and Soak • Temperature min. (T _{smin}) | 100°C | 150°C |
| • Temperature max. (T _{smax}) | 150°C | 200°C |
| • Time (T _{smin} to T _{smax}) (t _s) | 60-120 Seconds | 60-120 Seconds |
| Average ramp up rate T _{smax} to T _p | 3°C/ Second Max. | 3°C/ Second Max. |
| Liquidous temperature (TL) Time at liquidous (tL) | 183°C 60-150 Seconds | 217°C 60-150 Seconds |
| Peak package body temperature (Tp)* | Table 1 | Table 2 |
| Time (t _p)** within 5 °C of the specified classification temperature (T _c) | 20 Seconds** | 30 Seconds** |
| Average ramp-down rate (T _p to T _{smax}) | 6°C/ Second Max. | 6°C/ Second Max. |
| Time 25°C to Peak Temperature | 6 Minutes Max. | 8 Minutes Max. |
| | | |

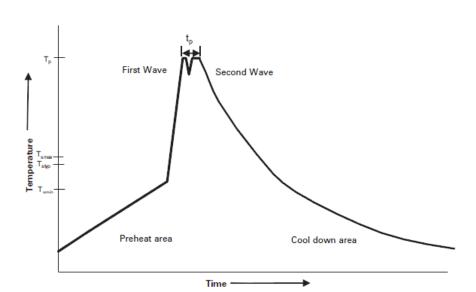


^{*} Tolerance for peak profile temperature (Γ_p) is defined as a supplier minimum and a user maximum.

** Tolerance for time at peak profile temperature (t_p) is defined as a supplier minimum and a user maximum.

Wave solder profile- Through-hole components

Reflow soldering not recommended



Reference EN 61760-1:2006

| Profile Feature | | Standard SnPb Solder | Lead (Pb) Free Solder |
|---------------------|------------------------------------------------------------------|-------------------------------------------|-------------------------------------------|
| Preheat | Temperature min. (T _{smin}) | 100°C | 100°C |
| | Temperature typ. (T_{styp}) | 120°C | 120°C |
| | Temperature max. (T _{smax}) | 130°C | 130°C |
| | Time (T _{smin} to T _{smax}) (t _s) | 70 seconds | 70 seconds |
| Δ preheat to | max Temperature | 150°C max. | 150°C max. |
| Peak tempera | sture (Tp)* | 235°C – 260°C | 250°C – 260°C |
| Time at peak | temperature (t _p) | 10 seconds max 5 seconds max each wave | 10 seconds max 5 seconds max each wave |
| Ramp-down r | ate | ~ 2 K/s min ~3.5 K/s typ ~5 K/s max | ~ 2 K/s min ~3.5 K/s typ ~5 K/s max |
| Time 25°C to | 25°C | 4 minutes | 4 minutes |

Manual solder

350°C, 4-5 seconds. (by soldering iron), generally manual, hand soldering is not recommended.



